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**Pritchard et al.**

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(54) **FORMING CROSS-COUPLED LINE SEGMENTS**

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(73) Assignee: **GLOBALFOUNDRIES Inc.**, Grand Cayman (KY)

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(21) Appl. No.: **14/167,071**

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(22) Filed: **Jan. 29, 2014**

(57) **ABSTRACT**

(65) **Prior Publication Data**

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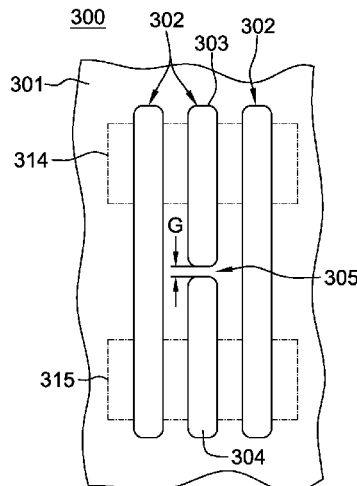
A method is provided for fabricating cross-coupled line segments for use, for instance, as a hard mask in fabricating cross-coupled gates of two or more transistors. Fabricating the structure includes: providing a sacrificial mandrel on the substrate, the sacrificial mandrel including a transverse gap through the mandrel separating the sacrificial mandrel into a first mandrel portion and a second mandrel portion; providing a sidewall spacer along sidewalls of the sacrificial mandrel, where sidewall spacers along sidewalls of the first mandrel portion and the second mandrel portion merge within the transverse gap and form a crossbar; and removing the sacrificial mandrel and selectively cutting the sidewall spacers to define the cross-coupled line segments from the sidewall spacers and crossbar. The transverse gap may be provided by directly printing the first and second mandrel portions spaced apart, or by cutting the sacrificial mandrel to provide the gap.

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**H01L 27/02** (2006.01)

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CPC ..... **H01L 21/3088** (2013.01); **H01L 21/3086** (2013.01); **H01L 27/0207** (2013.01)

(58) **Field of Classification Search**  
CPC ..... H01L 29/6659; H01L 21/8234; H01L 29/665; H01L 29/7833; H01L 29/666545  
USPC ..... 438/197; 257/401  
See application file for complete search history.

**18 Claims, 5 Drawing Sheets**



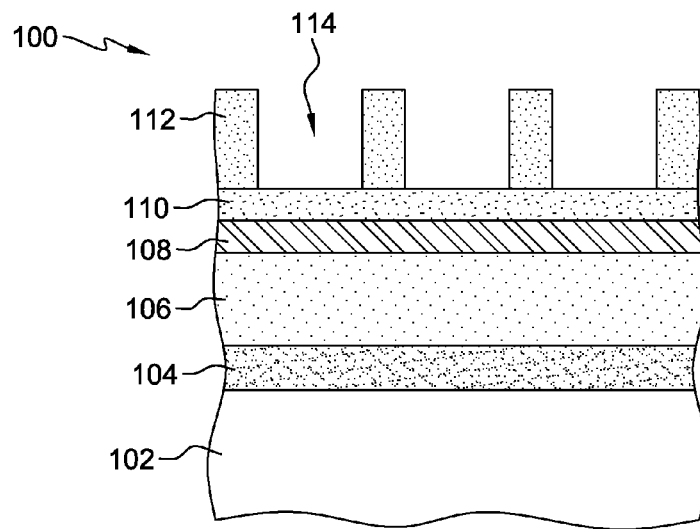


FIG. 1A

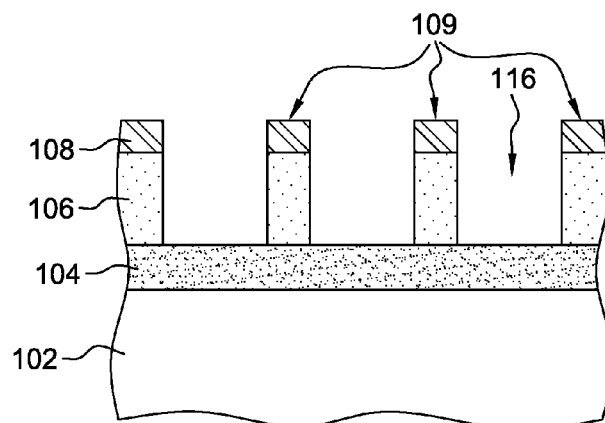


FIG. 1B

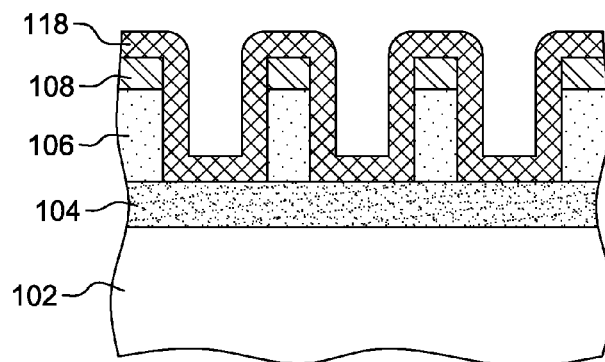


FIG. 1C

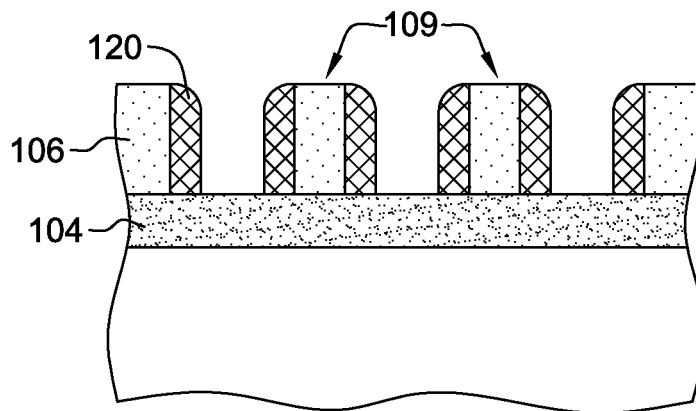


FIG. 1D

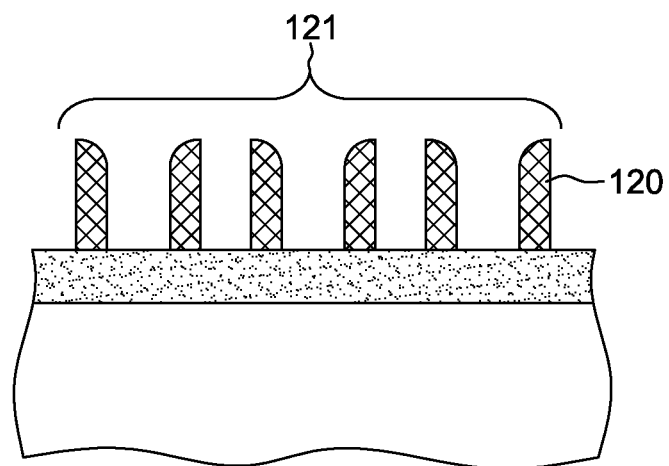


FIG. 1E

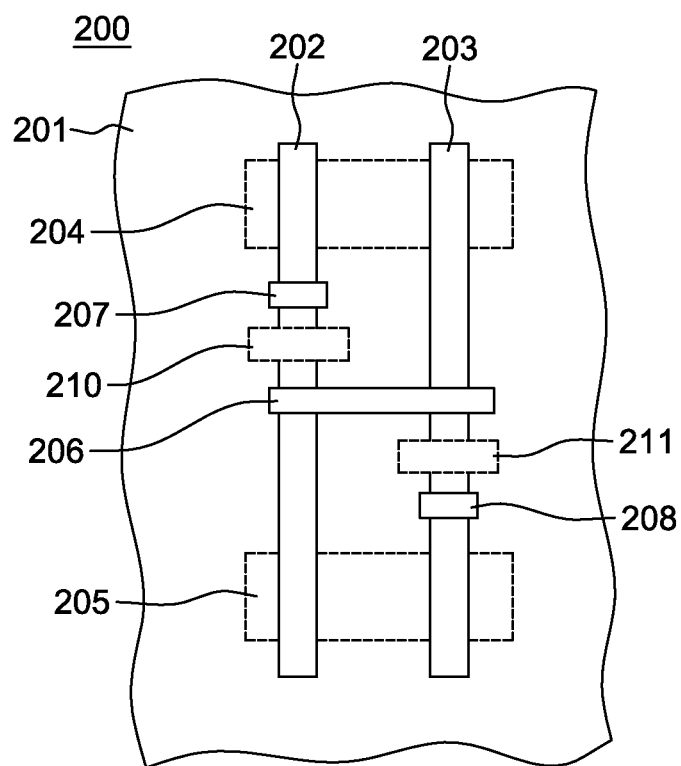


FIG. 2

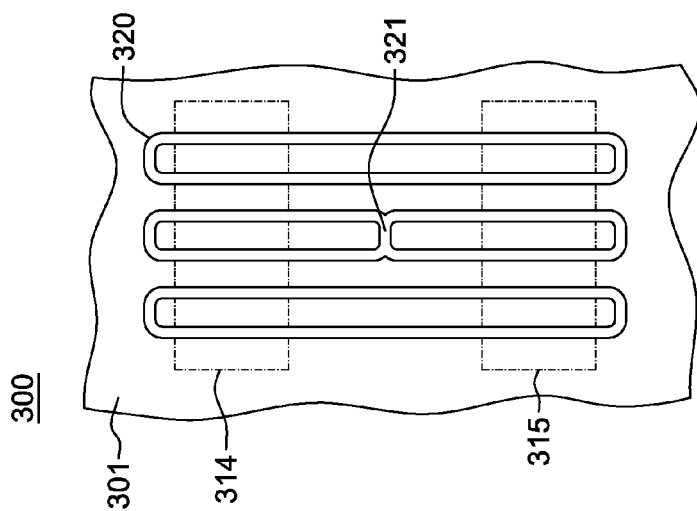


FIG. 3C

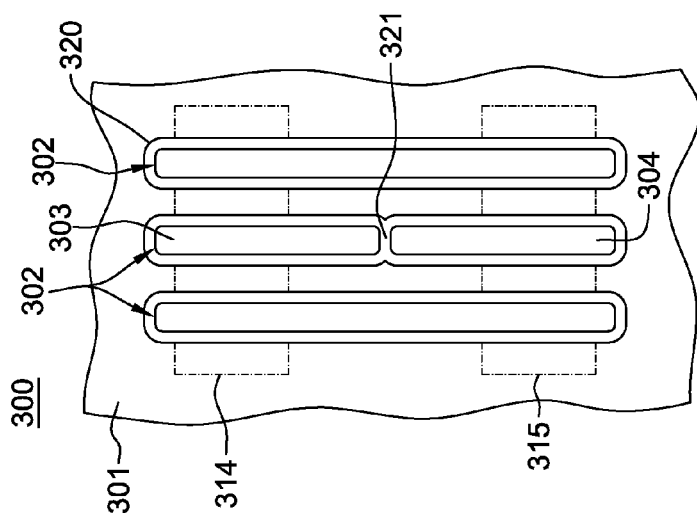


FIG. 3B

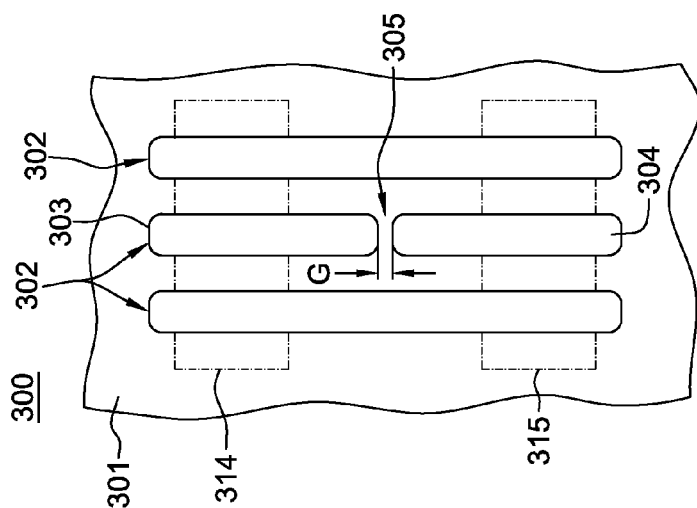


FIG. 3A

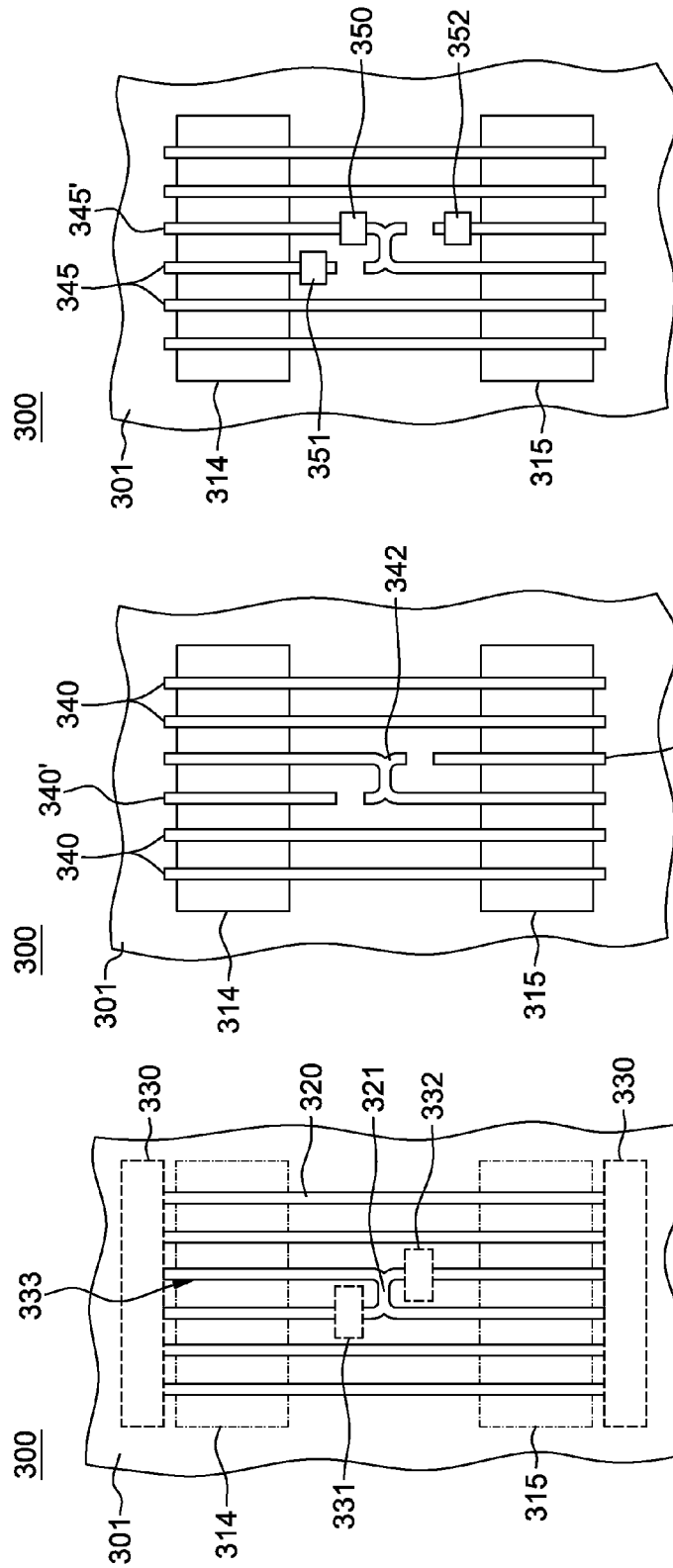


FIG. 3D

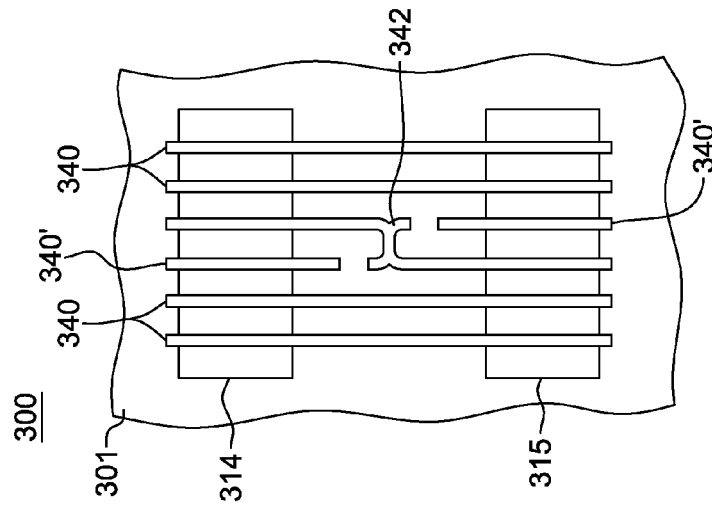


FIG. 3E

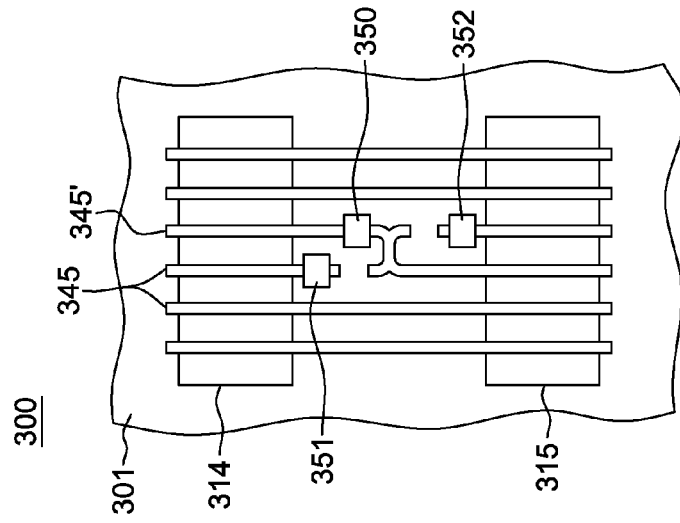


FIG. 3F

## FORMING CROSS-COUPLED LINE SEGMENTS

### BACKGROUND OF THE INVENTION

The present invention relates in general to semiconductor devices and to methods of fabricating semiconductor devices, and more particularly, to methods of fabricating in situ masks for use, for instance, in fabricating of one or more semiconductor devices.

As is known, semiconductor device fabrication typically involves the process of transferring a mask pattern to a wafer using an etching to remove unwanted material, for instance, to facilitate forming fin structures and/or gate structures of fin-type field-effect transistors (FINFETs) or to facilitate forming field-effect transistors (FETs) in general. This process is generally referred to as lithographic processing. As the size of technology nodes continues to decrease, significant challenges continue to arise due (in part) to issues related to traditional lithographic processing techniques, including issues related to mask formation.

### BRIEF SUMMARY

The shortcomings of the prior art are overcome, and additional advantages are provided through the provision, in one aspect, of a method which includes, for instance: fabricating a structure including cross-coupled line segments on a substrate, the fabricating including: providing a sacrificial mandrel on the substrate, the sacrificial mandrel including a transverse gap therethrough separating the sacrificial mandrel into a first mandrel portion and a second mandrel portion; providing a sidewall spacer along the sidewalls of the sacrificial mandrel, wherein sidewall spacers along sidewalls of the first mandrel portion and the second mandrel portion merge within the transverse gap and form a crossbar; and removing the sacrificial mandrel and selectively cutting the sidewall spacers to define the cross-coupled line segments from the sidewall spacers and the crossbar.

Additional features and advantages are realized through the techniques of the present invention. Other embodiments and aspects of the invention are described in detail herein and are considered a part of the claimed invention.

### BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS

One or more aspects of the present invention are particularly pointed out and distinctly claimed as examples in the claims at the conclusion of the specification. The foregoing and other objects, features, and advantages of the invention are apparent from the following detailed description taken in conjunction with the accompanying drawings in which:

FIGS. 1A-1E depict one example of a process for fabricating an in situ mask structure for use, for instance, in facilitating fabricating one or more circuit structures;

FIG. 2 depicts one example of a resultant circuit structure, with gates of adjacent transistors cross-coupled via a bridging electrical contact extending between the adjacent gates, in accordance with one or more aspects of the present invention; and

FIGS. 3A-3F depict one embodiment of a process for fabricating an in situ mask structure including cross-coupled line segments, and the use thereof in fabricating cross-coupled gates of a plurality of transistors, in accordance with one or more aspects of the present invention.

## DETAILED DESCRIPTION

Aspects of the present invention and certain features, advantages, and details thereof, are explained more fully below with reference to the non-limiting examples illustrated in the accompanying drawings. Descriptions of well-known materials, fabrication tools, processing techniques, etc., are omitted so as not to unnecessarily obscure the invention in detail. It should be understood, however, that the detailed description and the specific examples, while indicating aspects of the invention, are given by way of illustration only, and are not by way of limitation. Various substitutions, modifications, additions, and/or arrangements, within the spirit and/or scope of the underlying inventive concepts will be apparent to those skilled in the art from this disclosure.

In one aspect, circuit or device fabrication may involve using, for instance, lithography processing to facilitate transferring a mask pattern to one or more layers of a semiconductor wafer, which typically includes etching the wafer using the pattern to remove unwanted material. Lithography and etch processes may be used, for instance, to facilitate forming circuit features such as gate structures, fin structures, etc. In one example, a mask structure or pattern may be fabricated in situ using a self-aligned double patterning process (also referred to as sidewall image transfer processing). As integration density and complexity of semiconductor devices increases, significant fabrications challenges continue to arise with use of traditional lithographic techniques to pattern such features.

By way of example, FIGS. 1A-1E depict one embodiment of a process for fabricating an in situ, double-patterned lithography mask for use, for instance, in fabricating one or more circuit structures or features.

One embodiment of an intermediate structure **100** is depicted in FIG. 1A. This structure **100** includes a substrate **102**, such as a semiconductor substrate (for instance, a silicon wafer), and multiple layers disposed over substrate **102**. The multiple layers may include, for instance, a protective substrate mask layer **104**, a sacrificial spacing layer **106** disposed over protective substrate mask layer **104** and a protective hard mask layer **108** disposed over sacrificial spacing layer **106**. In one embodiment, sacrificial spacing layer **106** is a sacrificial spacing material such as, amorphous-carbon or any conventional organic material, which as understood in the art, may be employed to hold positions or form spacing for the in situ mask being formed. The noted layers of structure **100** of FIG. 1A may be formed using a variety of different materials and fabrication techniques, such as chemical vapor deposition (CVD), atomic layer deposition (ALD), physical vapor deposition (PVD) or plasma-enhanced versions of such processes. The thickness of the depicted layers may also vary, depending on the particular application.

By way of specific example, protective substrate mask layer **104** may be a layer of silicon nitride, formed over a silicon substrate **102**. Together these layers define one example of a substrate structure. In this example, protective hard mask layer **108** is formed over sacrificial spacing layer **106**. By way of further example, protective hard mask layer **108** may be formed of the same material as protective substrate mask layer **104**, with this same material being, in one example, silicon nitride (SiN) or silicon-oxynitride (SiON) formed by CVD processing. One or more lithographic processing steps may be performed to create sacrificial spacing structures from the multi-layer structure of FIG. 1A. These lithographic processing steps may include (for instance) providing an anti-reflective coating layer **110** over protective hard mask layer **108**, and providing a patterned photoresist

3

**112** over anti-reflective coating layer **110**. In one example, anti-reflective coating layer **110** may be a bottom anti-reflective coating (BARC) layer used to minimize pattern distortions due to reflections from the subsequent etching process. Patterned photoresist **112** includes openings **114**, which facilitate the subsequent patterning of protective hard mask layer **108**.

One or more lithographic etching processes are performed to transfer the pattern from patterned photoresist **112** of FIG. **1A** to the protective hard mask layer **108**. These process operations may include, for example, an anti-reflective-coating open step and a hard-mask open step. A final etch step is performed to obtain the structure depicted in FIG. **1B**, in which the patterned photoresist layer and anti-reflective coating layer of the structure of FIG. **1A** have been removed and the sacrificial spacing layer **106** (e.g., amorphous-carbon) has been etched to define a pattern of sacrificial spacing structures **109**. As shown, sacrificial spacing structures **109**, which may be separated by spaces **116**, may include protective hard masks **108** (disposed at the upper surfaces thereof) over sacrificial spacing layer or material **106**.

As depicted in FIG. **1C**, a sidewall spacer layer **118** is conformally provided over sacrificial spacing structures **109** and the substrate structure. Note that, in one embodiment, sidewall spacer layer **118** may be fabricated of a material that is substantially similar to the material defining protective hard masks **108** and/or protective substrate mask **104**. In one example, sidewall spacer layer **118** may include, for instance, a nitride (such as, for example,  $\text{Si}_3\text{N}_4$  or  $\text{SiN}$ ), conformally deposited using any of a variety of techniques, such as, for example, chemical vapor deposition (CVD) or atomic layer deposition (ALD).

As illustrated in FIG. **1D**, the sidewall spacer layer is etched, for instance, by any appropriate non-selective etching process, to form sidewall spacers **120**, along the sidewalls of sacrificial spacing structures **109**. As a part of this one-step etch process, the protective hard mask layer **108** (see FIG. **1C**) is removed, and the sidewall spacer layer is also etched from above protective substrate mask **104**, between sacrificial spacing structures **109**, resulting in exposing underlying protective substrate mask **104**.

Sacrificial spacing material/layer **106** (see FIG. **1D**) is subsequently etched away, as depicted in FIG. **1E**, by selective etch processing to create an in situ mask pattern **121** from the remaining sidewall spacers **120**. The mask pattern **121** created via this sidewall image transfer processing can then be employed in forming one or more structures within the substrate or wafer, such as gate structures or fin structures, of a circuit structure.

By way of example, FIG. **2** depicts one embodiment of a circuit structure **200** (or cell design) with cross-coupled gates electrically connected across the pitch. In particular, circuit structure **200** includes a substrate **201**, such as a semiconductor substrate or wafer, with parallel-extending, adjacent gates **202**, **203** of a plurality of transistors disposed, for instance, within multiple active device regions **204**, **205** of the circuit structure. In this embodiment, gates **202**, **203** are electrically connected or cross-coupled via a bridging electrical contact **206** formed between the gates **202**, **203**. Additionally, selective cuts **210**, **211** are provided in gates **202**, **203**, respectively, to segment the gates, and electrical contacts **207**, **208** are made to the remaining gate segments. Note that the circuit structure depicted in FIG. **2** is limited currently to middle-of-line (MOL) process integration, and potential implementations might require either novel materials, or more mask layers or contact stitching as gate pitch continues to decrease, which may be problematic for proper integration into the

4

circuit fabrication flow. The circuit structure of FIG. **2** would be particularly difficult to implement for technology nodes below 20 nm due to the need for the added connector.

Disclosed herein with reference to FIGS. **3A-3F** is another approach for forming cross-coupled gates using a modified version of the above-discussed self-aligned, double-patterning process. In this modified flow, cross-coupled line segments are directly created in situ during formation of the self-aligned, double-pattern mask, thus advantageously avoiding the integration issues with the approach depicted in FIG. **2**.

Referring to FIG. **3A**, one embodiment of a circuit or wafer **300** is depicted. In the intermediate stage shown, wafer **300** includes, for instance, a semiconductor substrate **301**, which may include as part of the substrate polysilicon material, and one or more active device regions **314**, **315** formed (or to be formed) within wafer **300**. A plurality of parallel-extending, elongate sacrificial mandrels **302** have been provided on substrate **301**. These elongate sacrificial mandrels **302** may be of any desired shape, length, width, etc., for the particular application of sidewall image transfer processing desired. In one example, the elongate sacrificial mandrels **302** may be formed as lines which extend across a significant portion of wafer **300** and overlie many active device regions, with active device regions **314**, **315** being shown by way of example only.

Referring collectively to FIGS. **3A & 3B**, one sacrificial mandrel **302** is shown to include a transverse gap **G 305** therethrough, separating or segmenting the sacrificial mandrel into a first mandrel portion **303** and a second mandrel portion **304**. The width of transverse gap **G 305** is controlled, and is selected with reference to the thickness of a sidewall spacer **320** (FIG. **3B**) formed around the sacrificial mandrels **302** using, for instance, conformal deposition, and etch processing, similar to that described above in connection with FIGS. **1C-1E**.

Forming transverse gap **G 305** of desired width in the sacrificial mandrel may involve directly forming the first mandrel portion and the second mandrel portion of the sacrificial mandrel with adjacent ends thereof spaced apart to define the transverse gap **G**. For instance, the broken or segmented sacrificial mandrel may be directly printed onto substrate **301** using, for instance, lithography processing. Alternatively, a gap of desired width may be formed by providing the sacrificial mandrel on the substrate, and then cutting the sacrificial mandrel transversely to define transverse gap **G 305** through the mandrel, for instance, using a special mandrel cut mask with an opening sized to the desired width of transverse gap **G**.

Note that although described herein with reference to providing a single sacrificial mandrel **302** with transverse gap **G**, the process may be repeated any number of times across the same mandrel or different mandrels in the same or different regions of the wafer **300**, as desired to obtain different configurations of an in situ mask having line segments and cross-coupled line segments, for instance, to implement a desired gate configuration for a plurality of transistors of a device, such as a microprocessor, memory circuit, optoelectronic circuit, electro-mechanical circuit, etc. In one specific example, the cross-coupled line segments (or resultant cross-coupled gates) disclosed herein could be employed in forming a standard cell design, such as for a flip-flop, which may be replicated, for instance, a large number of times in a memory circuit or device being fabricated.

By way of example, sidewall spacer **320** may include an oxide, or a nitride, such as, for example,  $\text{Si}_3\text{N}_4$ , or  $\text{SiN}$ , conformally deposited using any of a variety of techniques, such as, for example, chemical-vapor deposition (CVD) or atomic



5

layer deposition (ALD). The conformally deposited sidewall spacer layer is etched using any appropriate non-selective etching process to form the resultant sidewall spacers **320**, for instance, in a manner similar to that described above. As one example, sidewall spacers **320** may have a thickness in a range of 20 to 30 nanometers, and the width of transverse gap **G 305** is controlled or defined to be, in one example, approximately twice the thickness of the sidewall spacer **320**. Alternatively, the width of transverse gap **G** may be less than twice the thickness of the sidewall spacer to ensure merging of the sidewall spacer within the transverse gap. The sidewall merging results in formation of a crossbar **321** within the transverse gap cross-coupling line segments on different sides of the first and second mandrel portions **303**, **304**, as illustrated in FIG. 3B.

Continuing with FIGS. 3C-3F, the sidewall spacer pattern, with the formed "X" shape or crossbar **321** in the one sidewall spacer (or hard mask) is transferred to the wafer by, for instance, selectively removing the sacrificial mandrels **302** (see FIGS. 3A & 3B), leaving the mask pattern illustrated in FIG. 3C, and then using a cut mask with patterned openings to facilitate cutting **330** the rounded ends of the sidewall spacers to form the desired hard mask line segments, as well as optionally form openings or discontinuities **331**, **332** in selected line segments diagonally disposed across crossbar **321**, in order to define one or more cross-coupled line segments **333**. Note that openings or discontinuities **331**, **332** are provided by way of example only. In other implementations, one such opening or discontinuity may be provided in one of the line segments, or even no such openings or discontinuities **331**, **332** may be provided, again, depending on the desired implementation for the line segments. The patterned wafer **300** is depicted in FIG. 3E, which may be obtained by using the hard mask of FIG. 3D to selectively, anisotropically etch, for instance, underlying polysilicon on or within substrate **301** to define polysilicon lines **340** and cross-coupled lines **340'**, for instance, as part of a gate-last or replacement metal gate process flow. The polysilicon lines include unbroken gate lines **340**, and truncated gate lines **340'**, as well as one or more cross-coupled gates **342**. Once final gates **345**, **345'** are formed, electrical contacts **350**, **351**, **352**, etc., may be formed to the circuit structure.

Note that the electrical contact **350** to cross-coupled gate **345'** may be offset from the location of the crossbar (see FIGS. 3B-3D) connecting adjacent lines across the gate pitch. This electrical contact may advantageously be substantially identical to other electrical contacts, such as electrical contacts **351**, **352**, made to the depicted gate structures. Thus, electrical contact may be provided using conventional processing, without the use of any special contact layer, such as would be the case with the circuit structure of FIG. 2. Advantageously, with the processing described hereinabove with reference to FIGS. 3A-3F, it is possible to directly connect, for instance, polysilicon lines as one continuous structure using a merged crossbar. This process also advantageously results in reducing spacing between adjacent active device regions by facilitating formation of a smaller crossbar, that is, in comparison with an approach as described above in connection with FIG. 2. Thus, gate density for the resultant integrated circuit chip may be reduced, while also saving mask steps, and making it easier to place contacts to the resultant gate structures. There is no need for a bridging contact in the embodiment described above, thereby providing more flexibility in circuit design, for instance, in overlying a metal layer above the circuit structures.

The terminology used herein is for the purpose of describing particular embodiments only and is not intended to be

6

limiting of the invention. As used herein, the singular forms "a", "an" and "the" are intended to include the plural forms as well, unless the context clearly indicates otherwise. It will be further understood that the terms "comprise" (and any form of comprise, such as "comprises" and "comprising"), "have" (and any form of have, such as "has" and "having"), "include" (and any form of include, such as "includes" and "including"), and "contain" (and any form contain, such as "contains" and "containing") are open-ended linking verbs. As a result, a method or device that "comprises", "has", "includes" or "contains" one or more steps or elements possesses those one or more steps or elements, but is not limited to possessing only those one or more steps or elements. Likewise, a step of a method or an element of a device that "comprises", "has", "includes" or "contains" one or more features possesses those one or more features, but is not limited to possessing only those one or more features. Furthermore, a device or structure that is configured in a certain way is configured in at least that way, but may also be configured in ways that are not listed.

The corresponding structures, materials, acts, and equivalents of all means or step plus function elements in the claims below, if any, are intended to include any structure, material, or act for performing the function in combination with other claimed elements as specifically claimed. The description of the present invention has been presented for purposes of illustration and description, but is not intended to be exhaustive or limited to the invention in the form disclosed. Many modifications and variations will be apparent to those of ordinary skill in the art without departing from the scope and spirit of the invention. The embodiment was chosen and described in order to best explain the principles of one or more aspects of the invention and the practical application, and to enable others of ordinary skill in the art to understand one or more aspects of the invention for various embodiments with various modifications as are suited to the particular use contemplated.

What is claimed is:

1. A method comprising:

fabricating a structure comprising cross-coupled line segments on a substrate, the fabricating comprising:  
 providing a sacrificial mandrel on the substrate, the sacrificial mandrel comprising a transverse gap there-through separating the sacrificial mandrel into a first mandrel portion and a second mandrel portion;  
 providing a sidewall spacer along sidewalls of the sacrificial mandrel, wherein sidewall spacers along sidewalls of the first mandrel portion and the second mandrel portion merge within the transverse gap and form a crossbar;  
 removing the sacrificial mandrel and selectively cutting the sidewall spacers to define the cross-coupled line segments from the sidewall spacers and the crossbar; wherein providing the sacrificial mandrel comprises lithographically forming a plurality of parallel-extending, elongate sacrificial mandrels on the substrate, the sacrificial mandrel being one elongate sacrificial mandrel of the plurality of parallel-extending, elongate sacrificial mandrels; and  
 wherein providing the one elongate sacrificial mandrel comprises directly lithographically printing the first mandrel portion and the second mandrel portion on with the substrate, with adjacent ends thereof spaced apart to define the transverse gap through the sacrificial mandrel.

2. The method of claim 1, wherein providing the sacrificial mandrel comprises directly forming the first mandrel portion

7

and the second mandrel portion on the substrate with adjacent ends thereof spaced apart to define the transverse gap through the sacrificial mandrel.

3. The method of claim 2, wherein the transverse gap comprises a width which is approximately twice a thickness of the sidewall spacer, or less.

4. The method of claim 1, wherein providing the sacrificial mandrel comprises forming the sacrificial mandrel on the substrate and cutting the sacrificial mandrel to provide the transverse gap therethrough.

5. The method of claim 4, wherein the transverse gap comprises a width which is approximately twice a thickness of the sidewall spacer, or less.

6. The method of claim 1, wherein the transverse gap comprises a width which is approximately twice a thickness of the sidewall spacer.

7. The method of claim 1, wherein providing the sacrificial mandrel comprises lithographically forming the sacrificial mandrel on the substrate, the substrate comprising a semiconductor wafer.

8. The method of claim 7, wherein the sidewall spacer is a hard mask and the fabricating further comprises patterning at least a portion of the substrate using the cross-coupled line segments.

9. The method of claim 8, wherein the sidewall spacer comprises a nitride or an oxide.

10. The method of claim 8, wherein the substrate comprises polysilicon and the fabricating comprises patterning the polysilicon using, at least in part, the cross-coupled line segments.

11. The method of claim 1, wherein the transverse gap comprises a width which is approximately twice a thickness of the sidewall spacer, or less.

12. A method comprising:

fabricating a structure comprising cross-coupled line segments on a substrate, the fabricating comprising:

providing a sacrificial mandrel on the substrate, the sacrificial mandrel comprising a transverse gap therethrough separating the sacrificial mandrel into a first mandrel portion and a second mandrel portion;

providing a sidewall spacer along sidewalls of the sacrificial mandrel, wherein sidewall spacers along sidewalls of the first mandrel portion and the second mandrel portion merge within the transverse gap and form a crossbar;

removing the sacrificial mandrel and selectively cutting the sidewall spacers to define the cross-coupled line segments from the sidewall spacers and the crossbar; wherein providing the sacrificial mandrel comprises lithographically forming a plurality of parallel-extending, elongate sacrificial mandrels on the sub-

8

strate, the sacrificial mandrel being one elongate sacrificial mandrel of the plurality of parallel-extending, elongate sacrificial mandrels; and

wherein providing the one elongate sacrificial mandrel comprises lithographically forming the one elongate sacrificial mandrel on the substrate, and subsequently cutting the one elongate sacrificial mandrel to provide the transverse gap therethrough.

13. The method of claim 12, wherein the transverse gap comprises a width which is approximately twice a thickness of the sidewall spacer, or less.

14. A method comprising:

fabricating a structure comprising cross-coupled line segments on a substrate, the fabricating comprising:

providing a sacrificial mandrel on the substrate, the sacrificial mandrel comprising a transverse gap therethrough separating the sacrificial mandrel into a first mandrel portion and a second mandrel portion;

providing a sidewall spacer along sidewalls of the sacrificial mandrel, wherein sidewall spacers along sidewalls of the first mandrel portion and the second mandrel portion merge within the transverse gap and form a crossbar;

removing the sacrificial mandrel and selectively cutting the sidewall spacers to define the cross-coupled line segments from the sidewall spacers and the crossbar;

wherein the selectively cutting comprises forming a first cut through the sidewall spacer provided along the first mandrel portion and a second cut through the sidewall spacer provided along the second mandrel portion, the first cut and the second cut being on opposite sides of the sacrificial mandrel.

15. The method of claim 14, further comprising using the cross-coupled line segments as a mask in forming cross-coupled gates of a plurality of transistors.

16. The method of claim 15, wherein the fabricating further comprises forming an electrical contact to the cross-coupled gates at a location offset from a location of the crossbar.

17. The method of claim 15, wherein the fabricating further comprises forming a single electrical contact to the cross-coupled gates at a location, the location being offset from a location of the crossbar.

18. The method of claim 15, wherein the fabricating further comprises forming a plurality of transistors, and wherein the cross-coupled line segments facilitate forming cross-coupled gates of the plurality of transistors.

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